

Abstract of the Disclosure

A chip carrier film comprising a metal wiring formed on a surface of a base film, a first insulating film covering the metal wiring excluding a semiconductor chip connecting pad portion and a terminal connecting pad portion, a semiconductor chip connected to the semiconductor chip connecting pad portion of the metal wiring and mounted on the base film, and a second insulating film formed on a back face of the base film and having a different coefficient of curing shrinkage from that of the first insulating film. It is possible to obtain a chip carrier film capable of preventing the suspension of the base film from being generated by the self weight of the semiconductor chip when holding the base film by the delivery device and of carrying out mounting without a hindrance.